

Ablebond 84-1LMI

Epoxy; Epoxide
Henkel Ablestik

Message:

ABLEBOND® 84-1LMI die attach adhesive is designed for microelectronic chip bonding. This adhesive is ideal for application by automatic dispenser or hand probe.
ABLEBOND® 84-1LMI meets the requirements of MIL-STD-883, Method 5011.

General Information			
Filler / Reinforcement	Silver		
Features	Electrically Conductive		
	Low to No Outgassing		
Uses	Adhesives		
Agency Ratings	MIL Std. 883 Method 5011		
Appearance	Silver		
Forms	Paste		
Physical	Nominal Value	Unit	
pH	5.5		
Viscosity - Brookfield CP51 ¹ (25°C)	30.0	Pa · s	
Ionic Chloride	< 20	ppm	
Ionic Potassium	< 10	ppm	
Ionic Sodium	< 20	ppm	
Lap Shear - Al to Al (25°C)	12.0	MPa	
Shear Strength - Ag/Cu leadframe (Die) ² (25°C)	186	N	
Thixotropic Index ³	4.00		
Water Extract Conductivity	10.0	µS/cm	
Weight Loss on Heating (300°C)	0.19	%	
Work Life (25°C)	14.0	day	
Thermal	Nominal Value	Unit	Test Method
Glass Transition Temperature	103	°C	
CLTE - Flow			
< 103°C	5.5E-5	cm/cm/°C	
> 103°C	1.5E-4	cm/cm/°C	
Thermal Conductivity	2.4	W/m/K	ASTM C177
Electrical	Nominal Value	Unit	
Volume Resistivity	5.0E-4	ohms · cm	
Thermoset	Nominal Value	Unit	
Shelf Life			
-40°C	52	wk	

-10°C	26	wk
5°C	13	wk
Post Cure Time		
125°C	2.0	hr
150°C	1.0	hr
NOTE		
1.	Speed 5 rpm	
2.	2 X 2 mm Si die	
3.	(0.5/5 rpm	

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Recommended distributors for this material

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